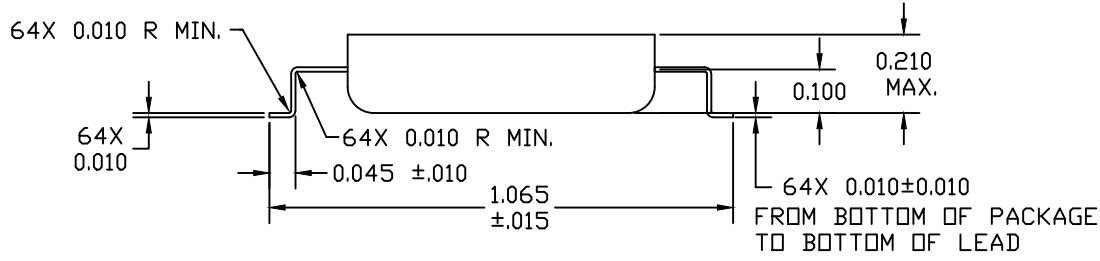
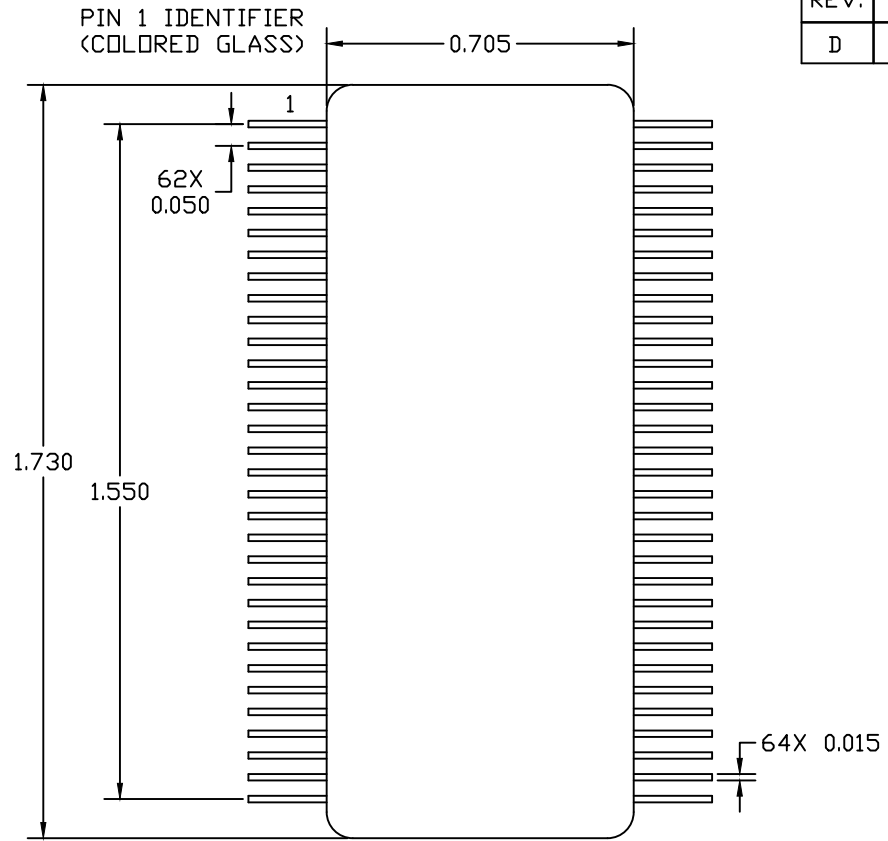


REV.	DESCRIPTION	ECN	DATE
D	INITIAL RELEASE	1120_ER6904	4-3-20



- NOTES:
- BEND LEADS USING DIE SET F020513
A) SET MICROMETER HEIGHT TO .110
 - STANDARD FINAL FINISH ON ALL TERMINALS IS
SOLDER ALLOY 63%Sn 37%Pb.

TITLE: CASE OUTLINE: 64 PIN FLATPACK	
DRAWING NO. D100693G-WEB	REV D

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